

RELIABILITY REPORT
FOR
MAX323xxA
PLASTIC ENCAPSULATED DEVICES

August 11, 2003

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Written by



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Conclusion

The MAX323 successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX323 is a precision, dual, SPST analog switch. It is a single-supply device designed to operate from +2.7V to +16V. The MAX324 has two normally open (NO) switches. Low power consumption (5 μ W) makes this part ideal for battery-powered equipment. This device offers low leakage currents (100pA max) and fast switching speeds (t_{ON} = 150ns max, t_{OFF} = 100ns max). The MAX324 also offers 5pC max charge injection.

B. Absolute Maximum Ratings

<u>Item</u>	<u>Rating</u>
Voltage Referenced to GND	
V+	-0.3V to +17V
IN_, COM_, NC_, NO_ (Note 1)	-0.3V to (V+ + 0.3V)
Continuous Current (any terminal)	30mA
Peak Current, COM_, NO_, NC_ (pulsed at 1ms, 10% duty cycle max)	100mA
Storage Temp.	-65°C to +150°C
Lead Temp. (10 sec.)	+300°C
Continuous Power Dissipation (TA = +70°C)	
8-Pin Plastic DIP	727mW
8-Pin Narrow SO	471mW
8-Pin uMAX	330mW
Derates above +70°C	
8-Pin Plastic DIP	9.09mW/°C
8-Pin Narrow SO	5.88mW/°C
8-Pin uMAX	4.10mW/°C

Note 1: Signals on NC, NO, COM, or IN exceeding V+ or V- are clamped by internal diodes. Limit forward diode current to maximum current rating.

II. Manufacturing Information

A. Description/Function:	Precision, Single-Supply, SPST Analog Switch
B. Process:	SG5 - Standard 5 micron silicon gate CMOS
C. Number of Device Transistors:	91
D. Fabrication Location:	Oregon, USA
E. Assembly Location:	Philippines, Malaysia, or Korea
F. Date of Initial Production:	December, 1994

III. Packaging Information

A. Package Type:	8-Lead NSO	8-Lead DIP	8-Lead uMAX
B. Lead Frame:	Copper	Copper	Copper
C. Lead Finish:	Solder Plate	Solder Plate	Solder Plate
D. Die Attach:	Silver-filled Epoxy	Silver-filled Epoxy	Silver-filled Epoxy
E. Bondwire:	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)	Gold (1.3 mil dia.)
F. Mold Material:	Epoxy with silica filler	Epoxy with silica filler	Epoxy with silica filler
G. Assembly Diagram:	# 05-0301-0688	# 05-0301-0687	# 05-0301-0689
H. Flammability Rating:	Class UL94-V0	Class UL94-V0	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard JESD22-A112:	Level 1	Level 1	Level 1

IV. Die Information

A. Dimensions:	55 x 73 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	5 microns (as drawn)
F. Minimum Metal Spacing:	5 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Jim Pedicord (Manager, Reliability Operations)
Bryan Preeshl (Executive Director of QA)
Kenneth Huening (Vice President)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% For all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in **Table 1**. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{192 \times 4389 \times 880 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

└ Temperature Acceleration factor assuming an activation energy of 0.8eV

$$\lambda = 1.23 \times 10^{-9} \quad \lambda = 1.23 \text{ F.I.T. (60\% confidence level @ 25°C)}$$

This low failure rate represents data collected from Maxim's reliability qualification and monitor programs. Maxim also performs weekly Burn-In on samples from production to assure reliability of its processes. The reliability required for lots which receive a burn-in qualification is 59 F.I.T. at a 60% confidence level, which equates to 3 failures in an 80 piece sample. Maxim performs failure analysis on rejects from lots exceeding this level. The attached Burn-In Schematic (Spec. # 06-5091) shows the static circuit used for this test. Maxim also performs 1000 hour life test monitors quarterly for each process. This data is published in the Product Reliability Report (**RR-1K**).

B. Moisture Resistance Tests

Maxim evaluates pressure pot stress from every assembly process during qualification of each new design. Pressure Pot testing must pass a 20% LTPD for acceptance. Additionally, industry standard 85°C/85%RH or HAST tests are performed quarterly per device/package family.

C. E.S.D. and Latch-Up Testing

The AG69-3 die type has been found to have all pins able to withstand a transient pulse of $\pm 2000\text{V}$, per Mil-Std-883 Method 3015 (reference attached ESD Test Circuit). Latch-Up testing has shown that this device withstands a current of $\pm 250\text{mA}$.

Table 1
Reliability Evaluation Test Results

MAX323xxA

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	PACKAGE	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)					
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality		880	0
Moisture Testing (Note 2)					
Pressure Pot	Ta = 121°C P = 15 psi. RH= 100% Time = 168hrs.	DC Parameters & functionality	DIP	77	0
			NSO	77	0
			uMAX	77	0
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality		77	0
Mechanical Stress (Note 2)					
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality		77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data

Attachment #1

TABLE II. Pin combination to be tested. 1/ 2/

	Terminal A (Each pin individually connected to terminal A with the other floating)	Terminal B (The common combination of all like-named pins connected to terminal B)
1.	All pins except V_{PS1} 3/	All V_{PS1} pins
2.	All input and output pins	All other input-output pins

1/ Table II is restated in narrative form in 3.4 below.

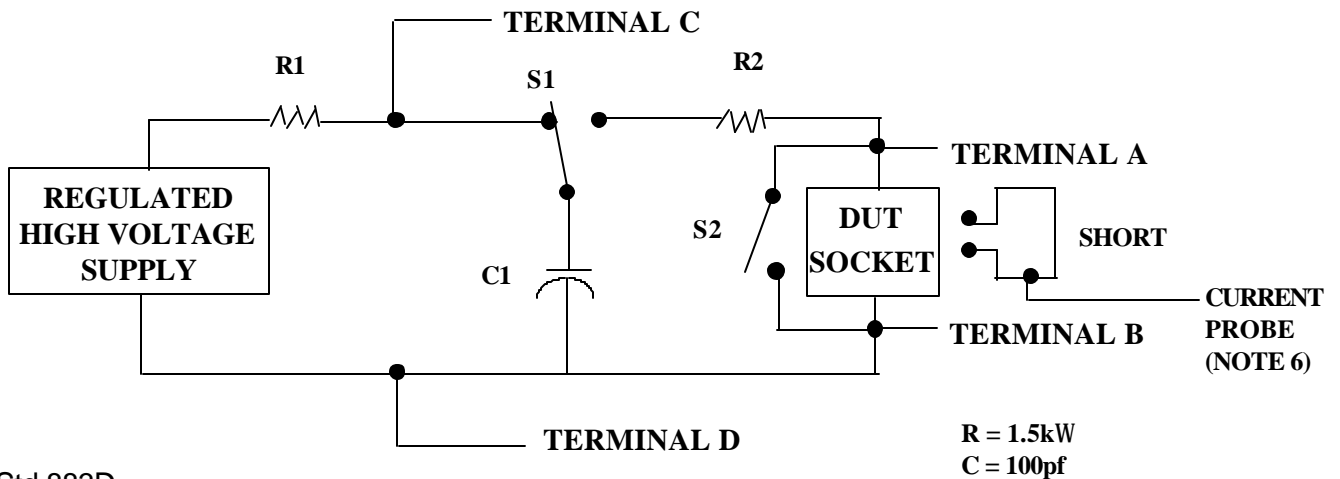
2/ No connects are not to be tested.

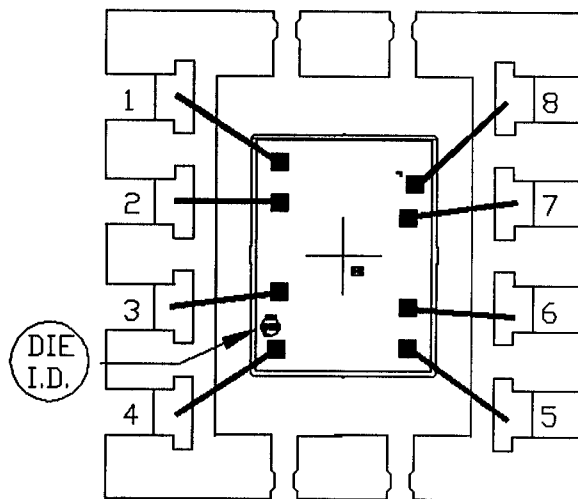
3/ Repeat pin combination I for each named Power supply and for ground

(e.g., where V_{PS1} is V_{DD} , V_{CC} , V_{SS} , V_{BB} , GND, $+V_S$, $-V_S$, V_{REF} , etc).

3.4 Pin combinations to be tested.

- a. Each pin individually connected to terminal A with respect to the device ground pin(s) connected to terminal B. All pins except the one being tested and the ground pin(s) shall be open.
- b. Each pin individually connected to terminal A with respect to each different set of a combination of all named power supply pins (e.g., V_{SS1} , or V_{SS2} or V_{SS3} or V_{CC1} , or V_{CC2}) connected to terminal B. All pins except the one being tested and the power supply pin or set of pins shall be open.
- c. Each input and each output individually connected to terminal A with respect to a combination of all the other input and output pins connected to terminal B. All pins except the input or output pin being tested and the combination of all the other input and output pins shall be open.



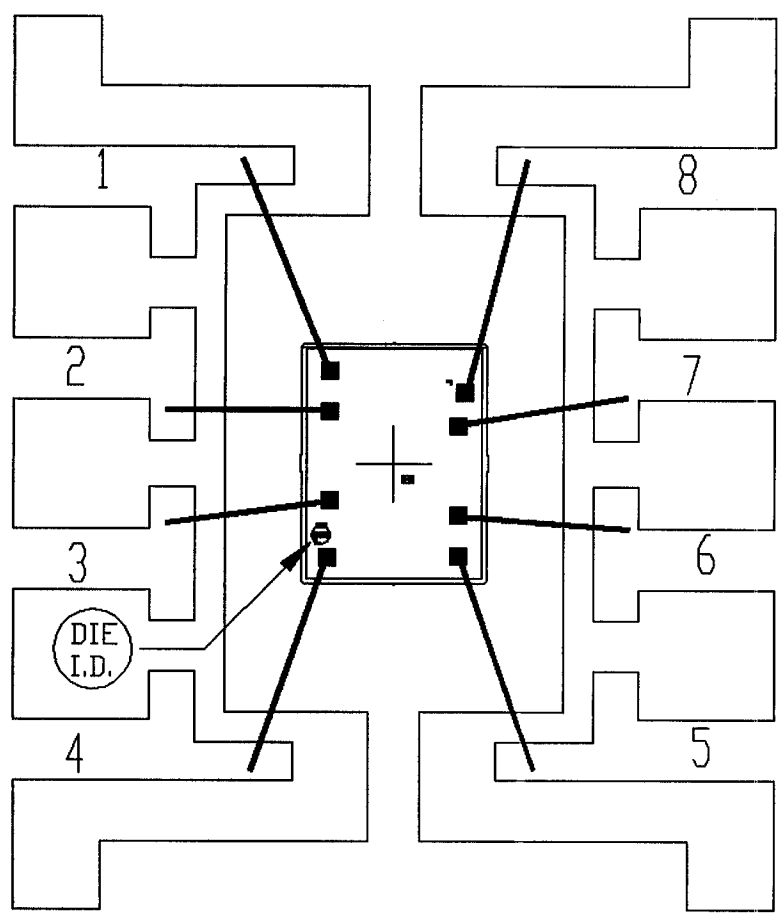



PKG. CODE:	U8-1	
CAV./PAD SIZE:	68X94	PKG. DESIGN

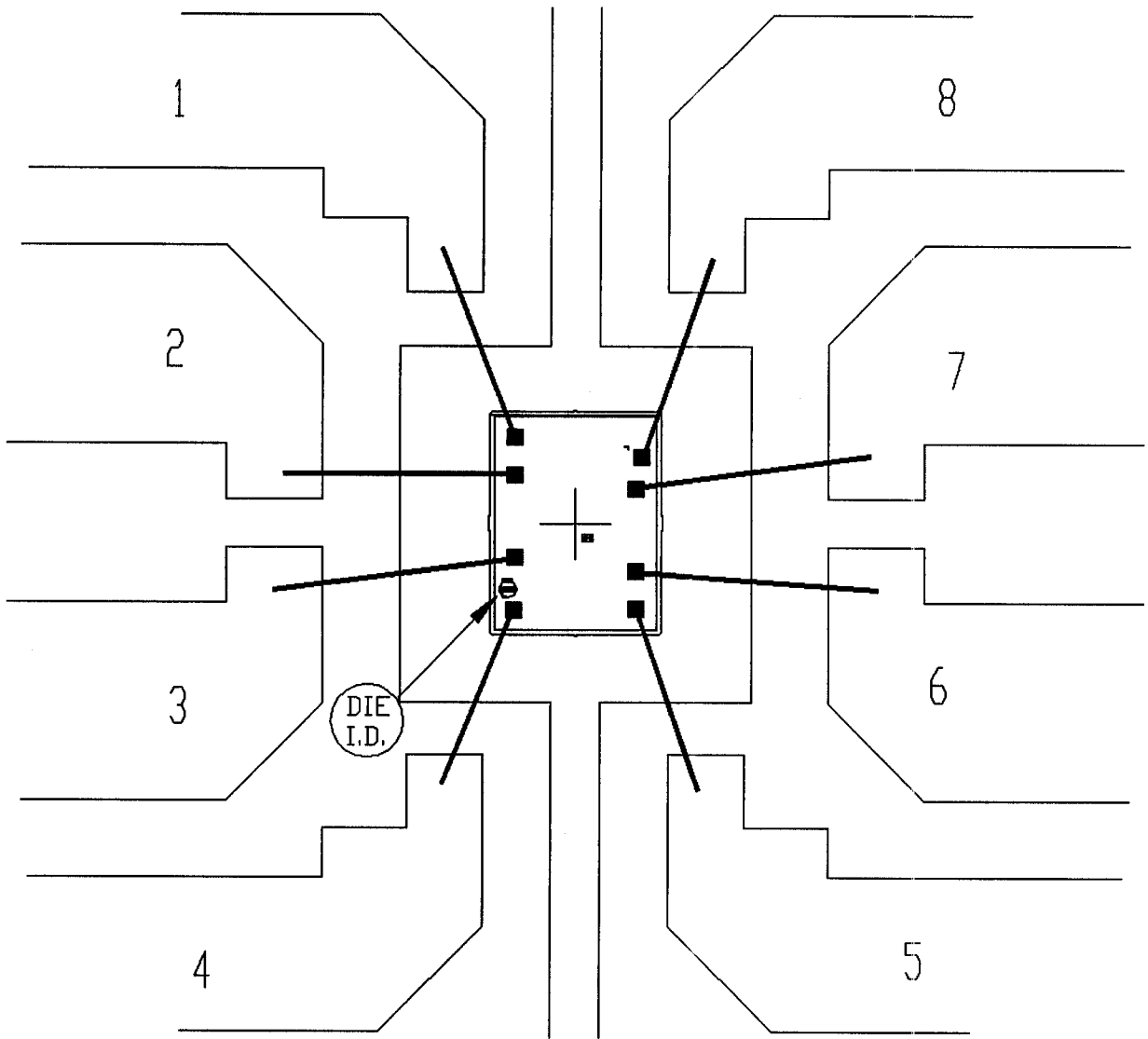
APPROVALS

DATE

MAXIM	
BUILDSHEET NUMBER:	REV.:
05--0301-0689	A



PKG.CODE: S8-4		APPROVALS	DATE		
CAV./PAD SIZE: 90 X 130	PKG. DESIGN			BUILDSHEET NUMBER: 05-0301-0688	REV.: A



PKG.CODE: P8-1

CAV./PAD SIZE: 100 X 100

PKG.
DESIGN

APPROVALS

DATE

MAXIM

BUILDSHEET NUMBER:
05-0301-0687

REV.:
A

